

YK900P04

P-Channel Enhancement Mode Field Effect Transistor



康比電子
HORNBY ELECTRONIC

General Description

The YK900P04 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

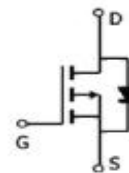
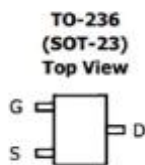
Application

- PWM application
- Load switch
- Power management

Features

$V_{DS} = -40V, I_D = -3A$
 $R_{DS(ON)} < 85m\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} < 100m\Omega @ V_{GS} = -4.5V$

- High power and current handling capability
- Lead free product is acquired
- Surface mount package



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
900P04	YK900P04	SOT-23	Ø180mm	8mm	3000 units

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DSS}	-40	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current-Continuous $V_{GS} = -4.5V$, @ $T_A = 25^\circ C$ (Note1)	I_D	-3	A
Drain Current –Pulsed	I_{DM}	-30	A
Maximum Power Dissipation @ $T_A = 25^\circ C$	P_D	2.5	W
Single pulse avalanche energy (Note 3)	EAS	11	mJ
Operating Junction and Storage Temperature Range	T_J	-55 ~ +150	$^\circ C$

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	100	$^\circ C/W$
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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	B _V DSS	V _{GS} = 0V, I _D = -250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V,V _{DS} = 0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _{DS} = -250μA	-1	-1.4	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} = -10V, I _{DS} = -3A	-	60	85	mΩ
		V _{GS} = -4.5V, I _{DS} = -2A	-	70	100	
Gate Resistance	R _g	V _{GS} = 0V, f = 1MHz	-	25	-	Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{GS} = 0V V _{DS} = -20V f = 1.0MHz	-	597	-	pF
Output Capacitance	C _{oss}		-	51	-	
Reverse Transfer Capacitance	C _{rss}		-	41	-	
Switching Characteristics						
Turn-on Delay Time (Note 4)	T _{d(on)}	V _{DD} = -20V V _{GS} = -10V I _D = -5A R _G = 2.5Ω	-	6.5		ns
Turn-on Rise Time (Note 4)	T _r		-	14		
Turn-Off Delay Time (Note 4)	T _{d(OFF)}		-	34		
Turn-Off Fall Time (Note 4)	T _f		-	18		
Total Gate Charge	Q _g	V _{DD} = -20V V _{GS} = -10V I _D = -3A	-	14.5	-	nC
Gate-Source Charge	Q _{gs}		-	2.4	-	
Gate-Drain Charge	Q _{gd}		-	2.1	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V _{SD}	I _S =-5A, V _{GS} =0V T _j = 25°C	-	-	-1.2	V

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating. The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH$
4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

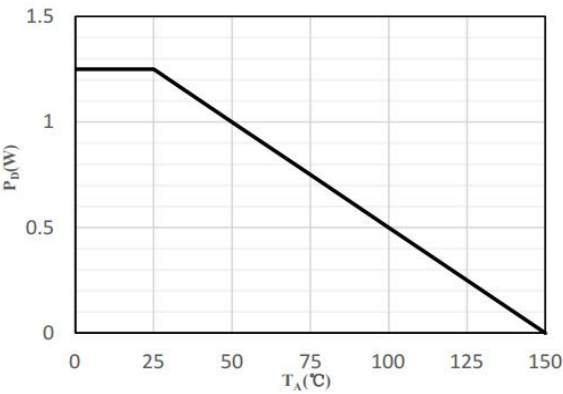


Fig 1 Power Dissipation

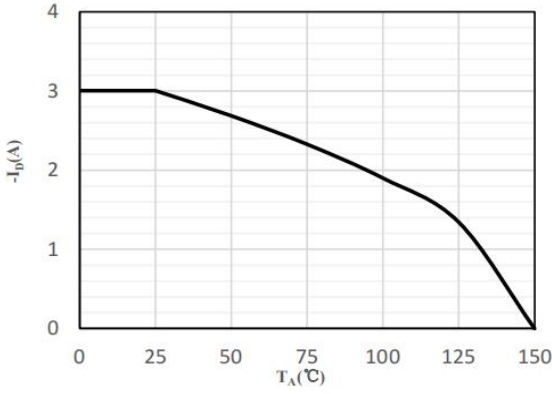


Fig 2 Drain Current

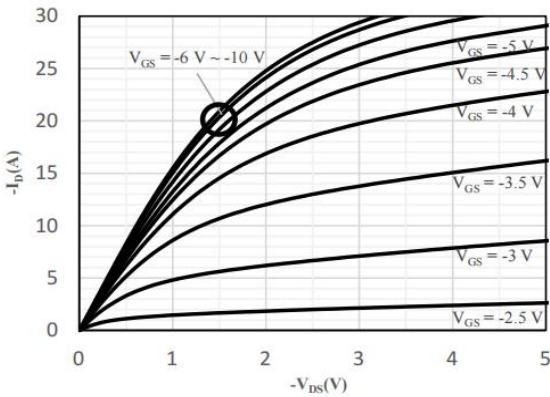


Fig 3 Typical Output Characteristics

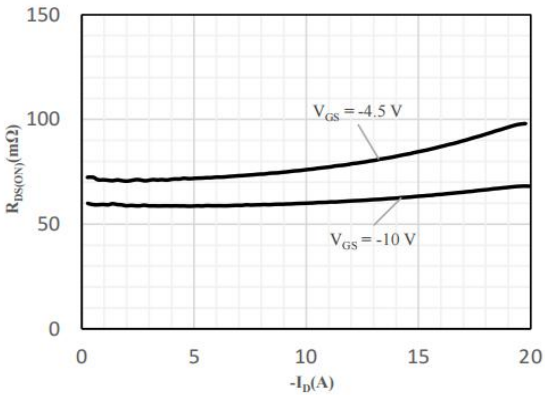


Fig 4 On-Resistance vs. Drain Current
and Gate Voltage

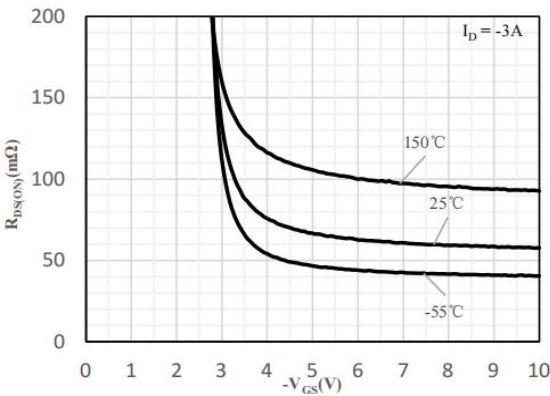


Fig 5 On-Resistance vs. Gate-Source Voltage

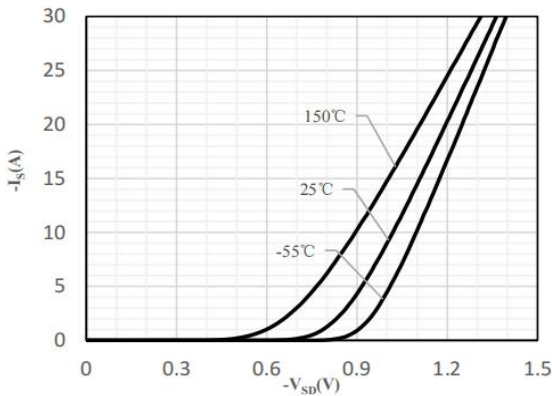


Fig 6 Body-Diode Characteristics

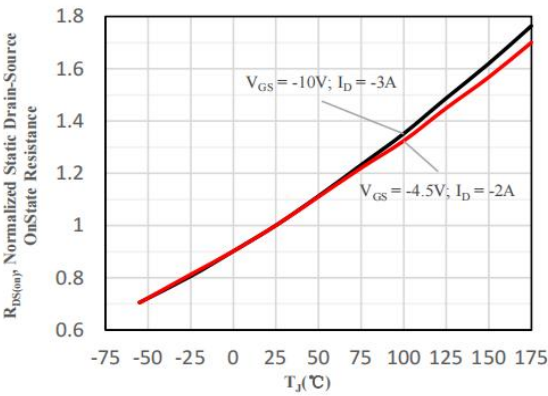


Fig 7 Normalized On-Resistance vs. Junction Temperature

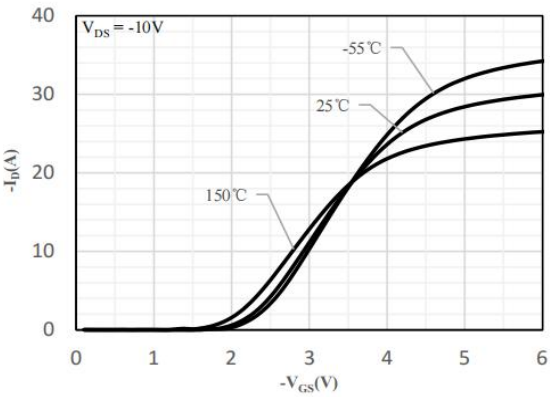


Fig 8 Transfer Characteristics

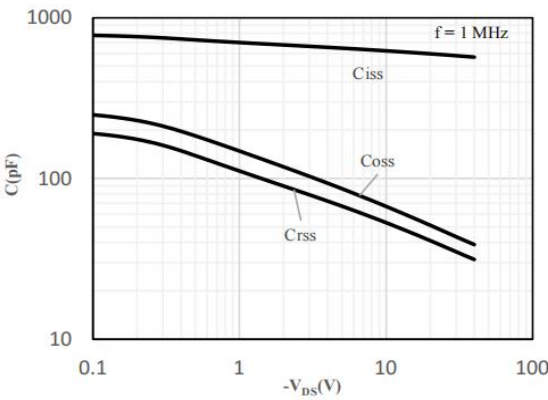


Fig 9 Capacitance Characteristics

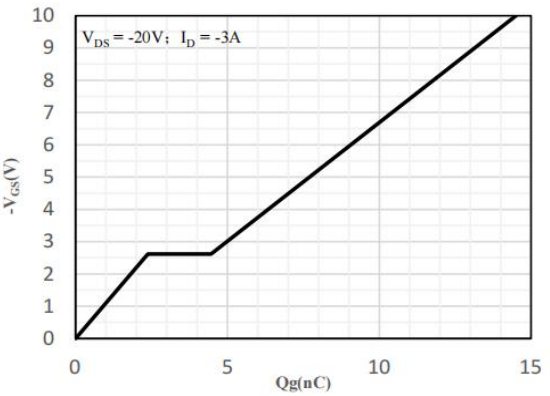


Fig 10 Gate-Charge Characteristics

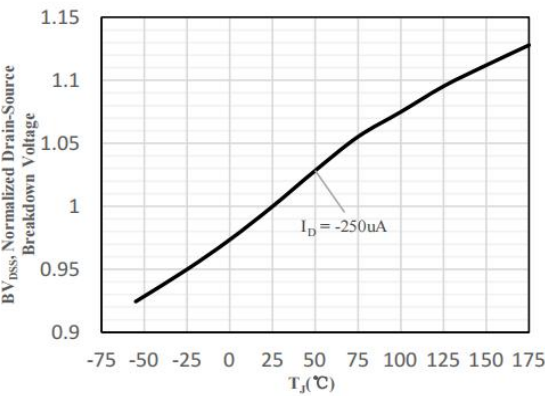


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

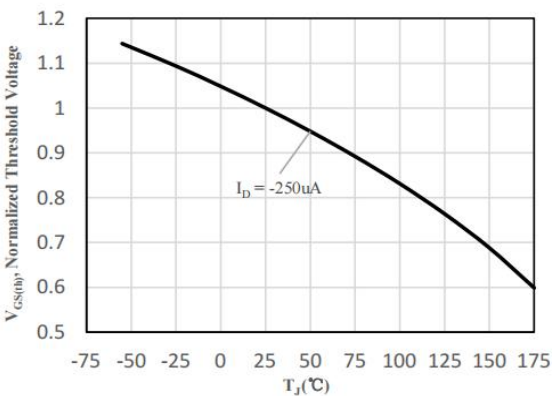


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

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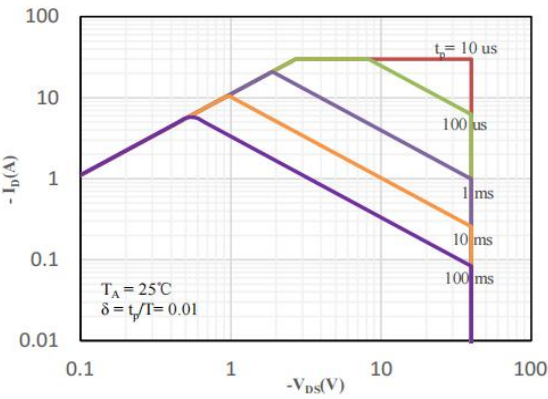


Fig 13 Safe Operation Area

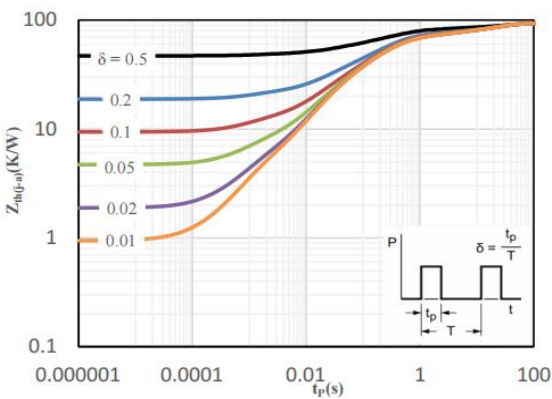
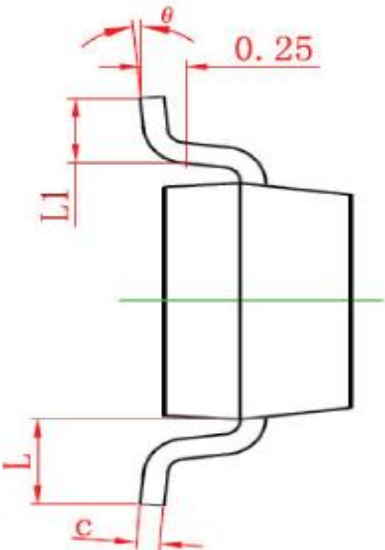
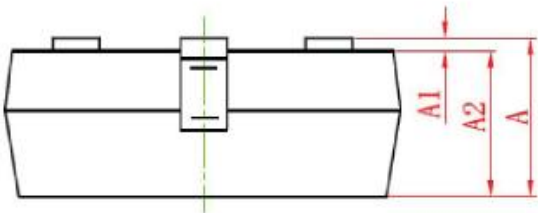
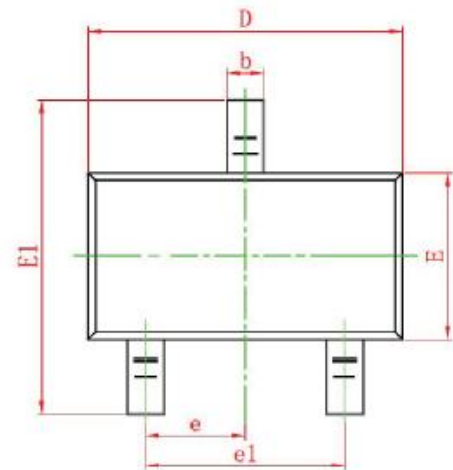


Fig 14 Maximum transient thermal impedance

SOT-23 Package Information



Symbol	Dimensions in Millimeters	
	MIN	MAX
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
C	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950 TYP	
e1	1.800	2.000
L	0.550 REF	
L1	0.300	0.500
θ	0°	8°